Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HPE 5945 48SFP28 8QSFP28 Switch(JQ074A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

HPE instructions for this template are available at MF877-01

Tool Description	Tool Size (if applicable)
Phillips screwdriver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the blank panel 1.
2. Remove film 1-2 from panel 1-1.
3. Unscrew the screws 2 and remove top cover 3.
4. Remove labels 3-1, 3-2, 3-3, 3-4, foams 3-5 and 3-6 from top cover
5. Unscrew the screws 4 and remove PCB 5, 6.
6. Unscrew the screws 7, and remove panel 8, PCB 9.
7. Remove dowel 5-1, dowel bushing 5-2, spring 5-3 and radiator 5-4 from pcb 5-5.
8. Unscrew the screws 6-1, remove dowel 6-2, dowel bushing 6-3, spring 6-4, radiator 6-5 and memories 6-6 from pcb 6-7.
9. Remove conductive foam 8-1, film 8-2 and 8-3 from panel 8-4.
10. Unscrew the screws 9-1, 9-2 and 9-3, and remove PCB 9-4 from PCB 9-5.
11. Unscrew the screws 10 and 12, remove fan transit cables 11 and shelter for wind 13.
12. Unscrew the screws 14, remove front panel 15 and PCB 16.
13. Remove film 17 and 18, shelding fingers 19, conductive foam 20.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

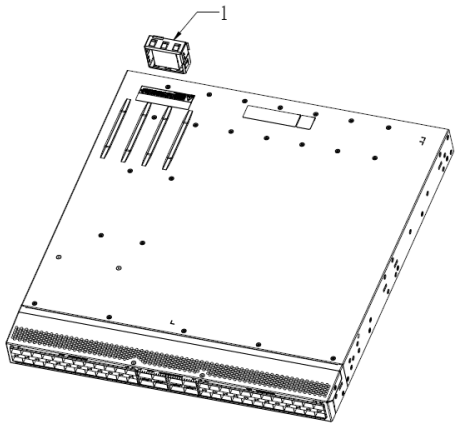

Figure 1 Remove blank panel

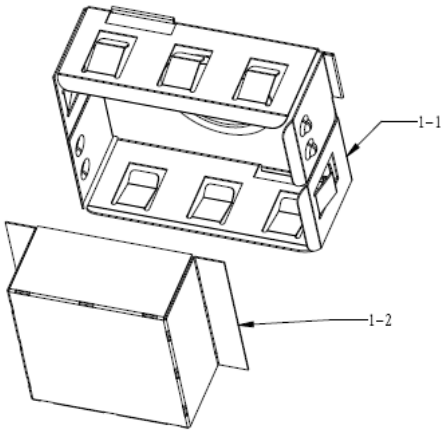

Figure 2 Treatments to blank panel

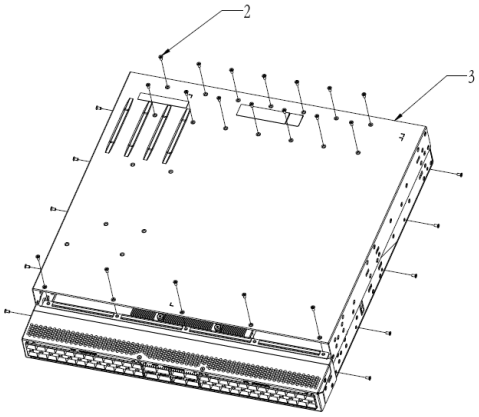

Figure 3 Treatments to the top cover

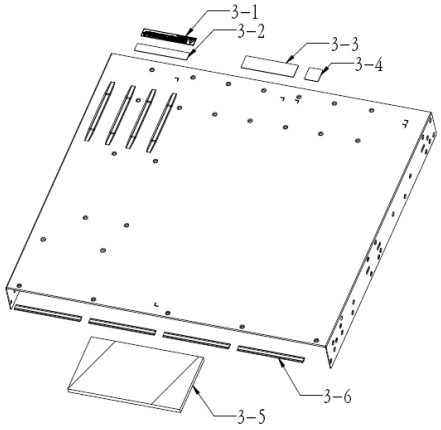

Figure 4 Treatments to the top cover t

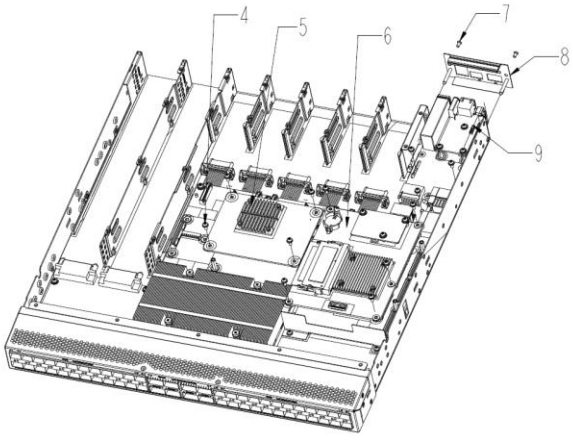

Figure 5 Treatments to the product

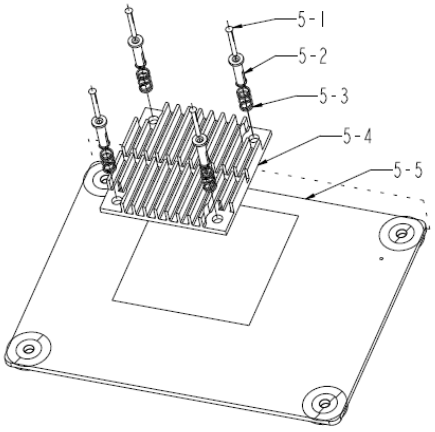

Figure 6 Treatments to PCB 5

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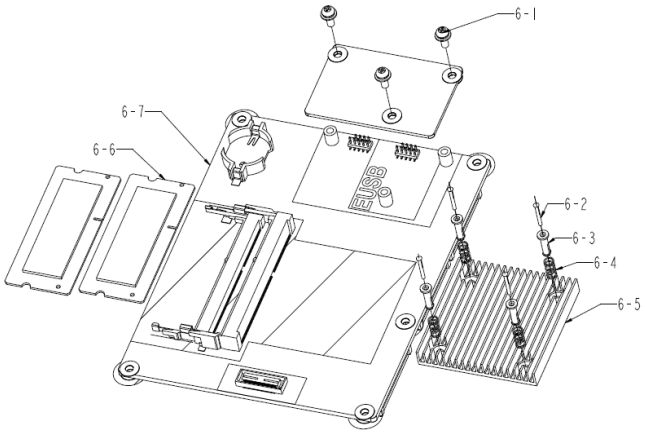

Figure 7 Treatments to PCB 6

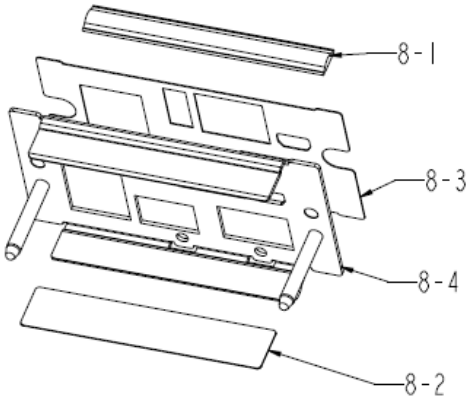

Figure 8 Treatments to panel 8

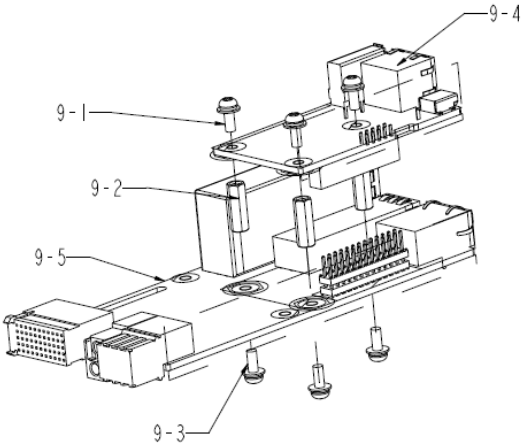

Figure 9 Treatments to the PCB 9

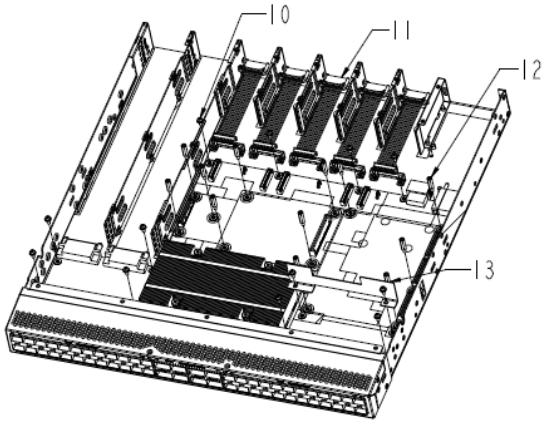

Figure 10 Treatments to the product

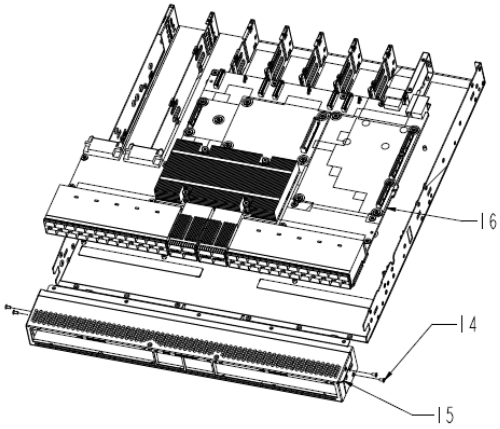

Figure 11 Treatments to the product

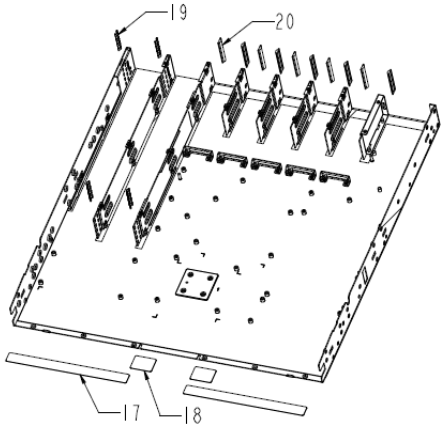

Figure 12 Treatments to the base

HPE instructions for this template are available at MF877-01